

# SKiiP 27MLI07E3V1



MiniSKiiP® 2

## 3-Level NPC IGBT-Module

### SKiiP 27MLI07E3V1

#### Features\*

- 650V Trench IGBTs
- Robust and soft diodes in CAL technology
- Highly reliable spring contacts for electrical connections
- UL recognised: File no. E63532
- NTC T-Sensor

#### Typical Applications

- Uninterruptible power supplies (UPS)
- Solar inverters

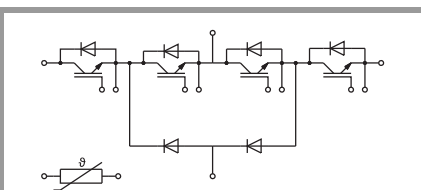
#### Remarks\*

- Max. case temperature limited to  $T_C = 125^\circ\text{C}$
- Product reliability results valid for  $T_j \leq 150^\circ\text{C}$  (recommended  $T_{j,op} = -40 \dots +150^\circ\text{C}$ )

#### Footnotes

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Absolute Maximum Ratings				
Symbol	Conditions		Values	Unit
<b>IGBT1</b>				
$V_{CES}$	$T_j = 25^\circ\text{C}$		650	V
$I_C$	$\lambda_{paste} = 0.8 \text{ W/(mK)}$	$T_s = 25^\circ\text{C}$	109	A
		$T_j = 175^\circ\text{C}$	87	A
$I_C$	$\lambda_{paste} = 2.5 \text{ W/(mK)}$	$T_s = 25^\circ\text{C}$	t.b.d.	A
		$T_j = 175^\circ\text{C}$	t.b.d.	A
$I_{Cnom}$			100	A
$I_{CRM}$			300	A
$V_{GES}$			-20 ... 20	V
$t_{psc}$	$V_{CC} = 360 \text{ V}, V_{GE} \leq 15 \text{ V}, T_j = 150^\circ\text{C}, V_{CES} \leq 650 \text{ V}$		6	$\mu\text{s}$
$T_j$			-40 ... 175	$^\circ\text{C}$
<b>IGBT2</b>				
$V_{CES}$	$T_j = 25^\circ\text{C}$		650	V
$I_C$	$\lambda_{paste} = 0.8 \text{ W/(mK)}$	$T_s = 25^\circ\text{C}$	109	A
		$T_j = 175^\circ\text{C}$	87	A
$I_C$	$\lambda_{paste} = 2.5 \text{ W/(mK)}$	$T_s = 25^\circ\text{C}$	t.b.d.	A
		$T_j = 175^\circ\text{C}$	t.b.d.	A
$I_{Cnom}$			100	A
$I_{CRM}$			300	A
$V_{GES}$			-20 ... 20	V
$t_{psc}$	$V_{CC} = 360 \text{ V}, V_{GE} \leq 15 \text{ V}, T_j = 150^\circ\text{C}, V_{CES} \leq 650 \text{ V}$		6	$\mu\text{s}$
$T_j$			-40 ... 175	$^\circ\text{C}$
<b>Diode1</b>				
$V_{RRM}$	$T_j = 25^\circ\text{C}$		650	V
$I_F$	$\lambda_{paste} = 0.8 \text{ W/(mK)}$	$T_s = 25^\circ\text{C}$	107	A
		$T_j = 175^\circ\text{C}$	84	A
$I_F$	$\lambda_{paste} = 2.5 \text{ W/(mK)}$	$T_s = 25^\circ\text{C}$	t.b.d.	A
		$T_j = 175^\circ\text{C}$	t.b.d.	A
$I_{FRM}$			200	A
$I_{FSM}$	10 ms, sin 180°, $T_j = 25^\circ\text{C}$		820	A
$T_j$			-40 ... 175	$^\circ\text{C}$
<b>Diode2</b>				
$V_{RRM}$	$T_j = 25^\circ\text{C}$		650	V
$I_F$	$\lambda_{paste} = 0.8 \text{ W/(mK)}$	$T_s = 25^\circ\text{C}$	107	A
		$T_j = 175^\circ\text{C}$	84	A
$I_F$	$\lambda_{paste} = 2.5 \text{ W/(mK)}$	$T_s = 25^\circ\text{C}$	t.b.d.	A
		$T_j = 175^\circ\text{C}$	t.b.d.	A
$I_{FRM}$			200	A
$I_{FSM}$	10 ms, sin 180°, $T_j = 25^\circ\text{C}$		820	A
$T_j$			-40 ... 175	$^\circ\text{C}$



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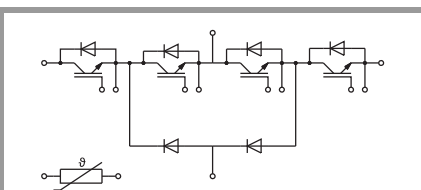
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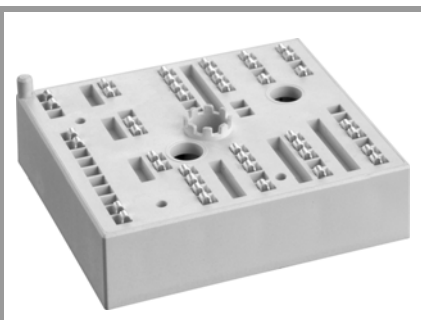
Absolute Maximum Ratings			
Symbol	Conditions	Values	Unit
<b>Diode5</b>			
$V_{RRM}$			V
$I_F$	$\lambda_{paste} = 0.8 \text{ W/(mK)}$	$T_s = 25^\circ\text{C}$	A
		$T_s = 70^\circ\text{C}$	A
$I_F$	$\lambda_{paste} = 2.5 \text{ W/(mK)}$	$T_s = 25^\circ\text{C}$	A
		$T_s = 70^\circ\text{C}$	A
$I_{FRM}$		t.b.d.	A
$I_{FSM}$		t.b.d.	A
$T_j$			$^\circ\text{C}$
<b>Module</b>			
$I_{t(RMS)}$	$T_{terminal} = 80^\circ\text{C}$ , 20A per spring	120	A
$T_{stg}$	module without TIM	-40 ... 125	$^\circ\text{C}$
$V_{isol}$	AC sinus 50 Hz, $t = 1 \text{ min}$	2500	V

Characteristics					
Symbol	Conditions	min.	typ.	max.	Unit
<b>IGBT1</b>					
$V_{CE(sat)}$	$I_C = 100 \text{ A}$ $V_{GE} = 15 \text{ V}$ chipelevel	$T_j = 25^\circ\text{C}$	1.45	1.85	V
		$T_j = 150^\circ\text{C}$	1.70	2.10	V
$V_{CE0}$	chipelevel	$T_j = 25^\circ\text{C}$	0.90	1.00	V
		$T_j = 150^\circ\text{C}$	0.82	0.90	V
$r_{CE}$	$V_{GE} = 15 \text{ V}$ chipelevel	$T_j = 25^\circ\text{C}$	5.5	8.5	$\text{m}\Omega$
		$T_j = 150^\circ\text{C}$	8.8	12	$\text{m}\Omega$
$V_{GE(th)}$	$V_{GE} = V_{CE}$ , $I_C = 1.6 \text{ mA}$	5	5.8	6.5	V
$I_{CES}$	$V_{GE} = 0 \text{ V}$ , $V_{CE} = 650 \text{ V}$ , $T_j = 25^\circ\text{C}$			1	mA
$C_{ies}$	$V_{CE} = 25 \text{ V}$ $V_{GE} = 0 \text{ V}$	$f = 1 \text{ MHz}$	6.16		nF
$C_{oes}$		$f = 1 \text{ MHz}$	0.38		nF
$C_{res}$		$f = 1 \text{ MHz}$	0.18		nF
$Q_G$	$V_{GE} = -8 \text{ V} \dots +15 \text{ V}$		800		nC
$R_{Gint}$	$T_j = 25^\circ\text{C}$		2.0		$\Omega$
$t_{d(on)}$	$V_{CE} = 300 \text{ V}$ $I_C = 100 \text{ A}$	$T_j = 150^\circ\text{C}$	114		ns
$t_r$		$T_j = 150^\circ\text{C}$	59		ns
$E_{on}$	$V_{GE} = +15/-15 \text{ V}$ $R_{G on} = 4 \Omega$	$T_j = 150^\circ\text{C}$	4.2		mJ
$t_{d(off)}$		$T_j = 150^\circ\text{C}$	259		ns
$t_f$	$R_{G off} = 2.1 \Omega$ $di/dt_{on} = 1715 \text{ A}/\mu\text{s}$ $di/dt_{off} = 1420 \text{ A}/\mu\text{s}$	$T_j = 150^\circ\text{C}$	66		ns
$E_{off}$		$T_j = 150^\circ\text{C}$	4.2		mJ
$R_{th(j-s)}$	per IGBT, $\lambda_{paste} = 0.8 \text{ W/(mK)}$		0.6		K/W
$R_{th(j-s)}$	per IGBT, $\lambda_{paste} = 2.5 \text{ W/(mK)}$		t.b.d.		K/W



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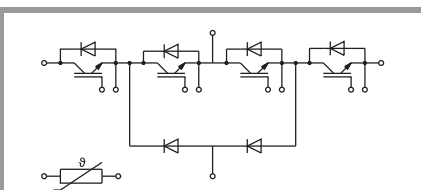
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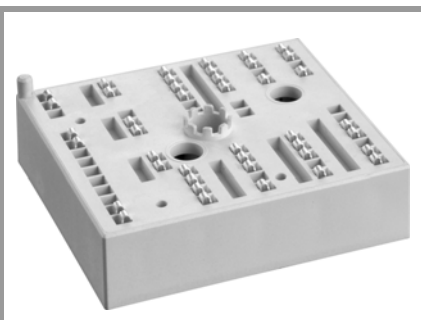
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Characteristics		min.	typ.	max.	Unit
<b>Symbol</b>	<b>Conditions</b>				
<b>IGBT2</b>					
$V_{CE(sat)}$	$I_C = 100\text{ A}$ $V_{GE} = 15\text{ V}$ chipelevel	$T_j = 25^\circ\text{C}$	1.45	1.85	V
		$T_j = 150^\circ\text{C}$	1.70	2.10	V
$V_{CE0}$	chipelevel	$T_j = 25^\circ\text{C}$	0.90	1.00	V
		$T_j = 150^\circ\text{C}$	0.82	0.90	V
$r_{CE}$	$V_{GE} = 15\text{ V}$ chipelevel	$T_j = 25^\circ\text{C}$	5.5	8.5	m $\Omega$
		$T_j = 150^\circ\text{C}$	8.8	12	m $\Omega$
$V_{GE(th)}$	$V_{GE} = V_{CE}, I_C = 1.6\text{ mA}$	5	5.8	6.5	V
$I_{CES}$	$V_{GE} = 0\text{ V}, V_{CE} = 650\text{ V}, T_j = 25^\circ\text{C}$			1	mA
$C_{ies}$	$V_{CE} = 25\text{ V}$ $V_{GE} = 0\text{ V}$	$f = 1\text{ MHz}$	6.16		nF
$C_{oes}$		$f = 1\text{ MHz}$	0.38		nF
$C_{res}$		$f = 1\text{ MHz}$	0.18		nF
$Q_G$	$V_{GE} = -8\text{ V} \dots +15\text{ V}$		800		nC
$R_{Gint}$	$T_j = 25^\circ\text{C}$		2.0		$\Omega$
$t_{d(on)}$	$V_{CC} = 300\text{ V}$ $I_C = 100\text{ A}$	$T_j = 150^\circ\text{C}$	110		ns
$t_r$	$V_{GE} = +15/-15\text{ V}$	$T_j = 150^\circ\text{C}$	58		ns
$E_{on}$	$R_{G on} = 4\ \Omega$	$T_j = 150^\circ\text{C}$	1.8		mJ
$t_{d(off)}$	$R_{G off} = 2.1\ \Omega$	$T_j = 150^\circ\text{C}$	258		ns
$t_f$	$di/dt_{on} = 2035\text{ A}/\mu\text{s}$ $di/dt_{off} = 1425\text{ A}/\mu\text{s}$	$T_j = 150^\circ\text{C}$	77		ns
$E_{off}$		$T_j = 150^\circ\text{C}$	4		mJ
$R_{th(j-s)}$	per IGBT, $\lambda_{paste} = 0.8\text{ W}/(\text{mK})$		0.6		K/W
$R_{th(j-s)}$	per IGBT, $\lambda_{paste} = 2.5\text{ W}/(\text{mK})$		t.b.d.		K/W
<b>Diode1</b>					
$V_F = V_{EC}$	$I_F = 100\text{ A}$ $V_{GE} = 0\text{ V}$ chipelevel	$T_j = 25^\circ\text{C}$	1.40	1.76	V
		$T_j = 150^\circ\text{C}$	1.38	1.77	V
$V_{F0}$	chipelevel	$T_j = 25^\circ\text{C}$	1.04	1.24	V
		$T_j = 150^\circ\text{C}$	0.85	0.99	V
$r_F$	chipelevel	$T_j = 25^\circ\text{C}$	3.6	5.3	m $\Omega$
		$T_j = 150^\circ\text{C}$	5.3	7.8	m $\Omega$
$I_{RRM}$	$I_F = 100\text{ A}$	$T_j = 150^\circ\text{C}$	89		A
$Q_{rr}$	$di/dt_{off} = 1980\text{ A}/\mu\text{s}$ $V_R = 300\text{ V}$	$T_j = 150^\circ\text{C}$	13		$\mu\text{C}$
$E_{rr}$	$V_{GE} = +15/-15\text{ V}$	$T_j = 150^\circ\text{C}$	3.5		mJ
$R_{th(j-s)}$	per Diode, $\lambda_{paste} = 0.8\text{ W}/(\text{mK})$		0.8		K/W
$R_{th(j-s)}$	per Diode, $\lambda_{paste} = 2.5\text{ W}/(\text{mK})$		t.b.d.		K/W
<b>Diode2</b>					
$V_F = V_{EC}$	$I_F = 100\text{ A}$ $V_{GE} = 0\text{ V}$ chipelevel	$T_j = 25^\circ\text{C}$	1.40	1.76	V
		$T_j = 150^\circ\text{C}$	1.38	1.77	V
$V_{F0}$	chipelevel	$T_j = 25^\circ\text{C}$	1.04	1.24	V
		$T_j = 150^\circ\text{C}$	0.85	0.99	V
$r_F$	chipelevel	$T_j = 25^\circ\text{C}$	3.6	5.3	m $\Omega$
		$T_j = 150^\circ\text{C}$	5.3	7.8	m $\Omega$
$I_{RRM}$	$I_F = 100\text{ A}$	$T_j = 150^\circ\text{C}$	86		A
$Q_{rr}$	$di/dt_{off} = 1780\text{ A}/\mu\text{s}$ $V_R = 300\text{ V}$	$T_j = 150^\circ\text{C}$	10.1		$\mu\text{C}$
$E_{rr}$ <sup>1)</sup>	$V_{GE} = +15/-15\text{ V}$	$T_j = 150^\circ\text{C}$	2		mJ
$R_{th(j-s)}$	per Diode, $\lambda_{paste} = 0.8\text{ W}/(\text{mK})$		0.8		K/W
$R_{th(j-s)}$	per Diode, $\lambda_{paste} = 2.5\text{ W}/(\text{mK})$		t.b.d.		K/W

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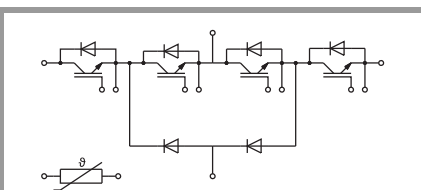
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#### Footnotes

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Characteristics					
Symbol	Conditions	min.	typ.	max.	Unit
<b>Diode5</b>					
$V_F = V_{EC}$					V
					V
$V_{F0}$					V
					V
$r_F$				0.00	mΩ
			0.00	0.00	mΩ
$I_{RRM}$	$I_F = \text{t.b.d. A}$		t.b.d.		A
$Q_{rr}$			t.b.d.		μC
$E_{rr}$	$V_R = 300 \text{ V}$ $V_{GE} = +15/-15 \text{ V}$		t.b.d.		mJ
$R_{th(j-s)}$	per Diode, $\lambda_{paste}=0.8 \text{ W/(mK)}$				K/W
$R_{th(j-s)}$	per Diode, $\lambda_{paste}=2.5 \text{ W/(mK)}$		t.b.d.		K/W
<b>Module</b>					
$L_{sCE1}$			-		nH
$L_{sCE2}$			-		nH
$R_{CC+EE}$					mΩ
		$T_s = 25^\circ\text{C}$			mΩ
		$T_s = 125^\circ\text{C}$			mΩ
$M_s$	to heat sink	2		2.5	Nm
$M_t$			-		Nm
			-		Nm
$w$			55		g
<b>Temperature Sensor</b>					
$R_{100}$	$T_c=100^\circ\text{C}$ ( $R_{25}=5 \text{ k}\Omega$ )		$493 \pm 5\%$		Ω
$B_{100/125}$	$R(T)=R_{100}\exp[B_{100/125}(1/T-1/T_{100})]$ ; $T[\text{K}]$		$3550 \pm 2\%$		K



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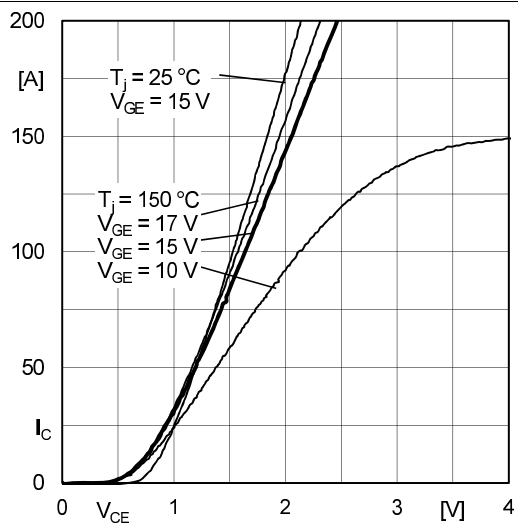


Fig. 1: Typ. IGBT1 output characteristic, incl.  $R_{CC'+EE'}$

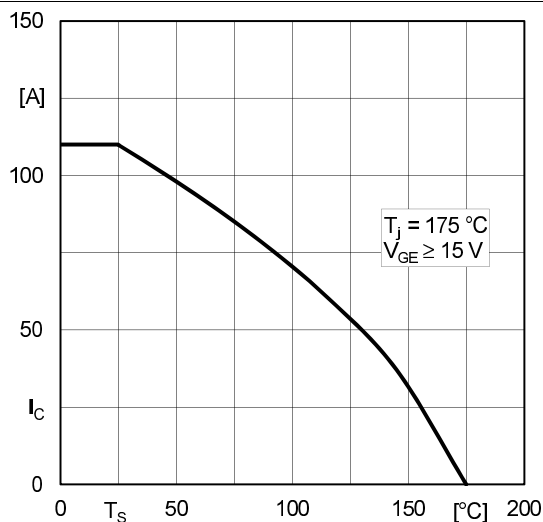


Fig. 2: Rated current vs. temperature  $I_C = f(T_S)$

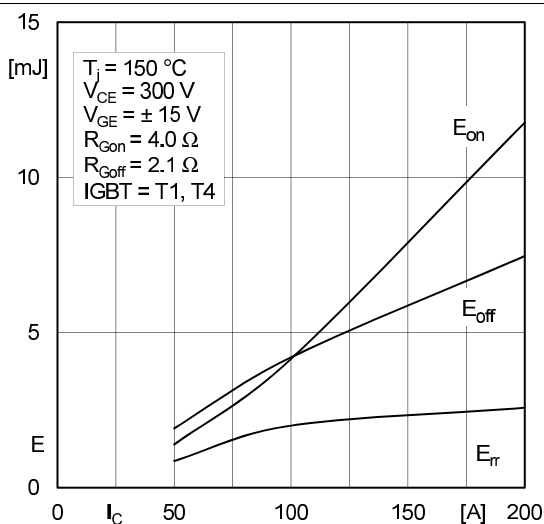


Fig. 3: Typ. IGBT1 & Diode5 turn-on /-off energy =  $f(I_C)$

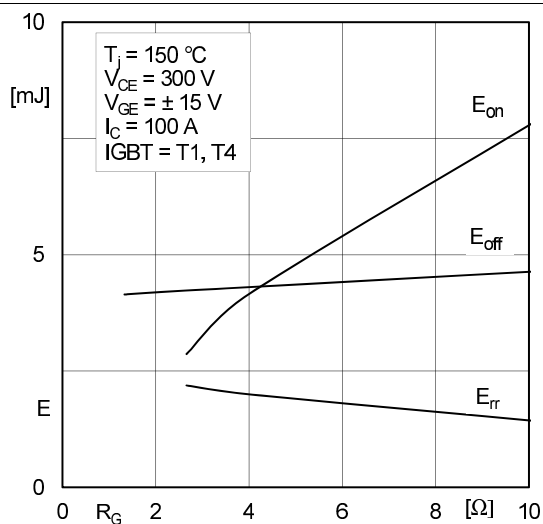


Fig. 4: Typ. IGBT1 & Diode5 turn-on /-off energy =  $f(R_G)$

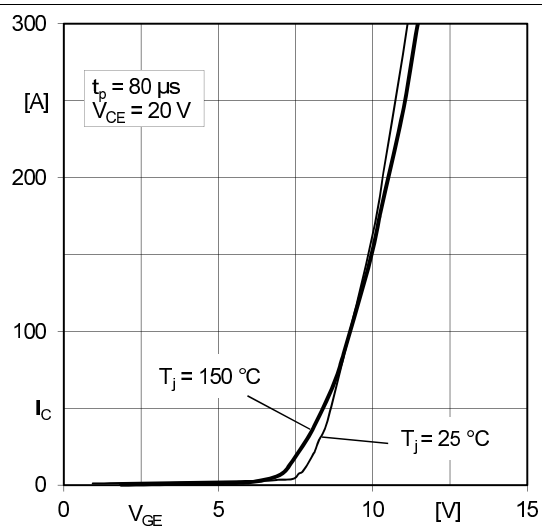


Fig. 5: Typ. IGBT1 transfer characteristic

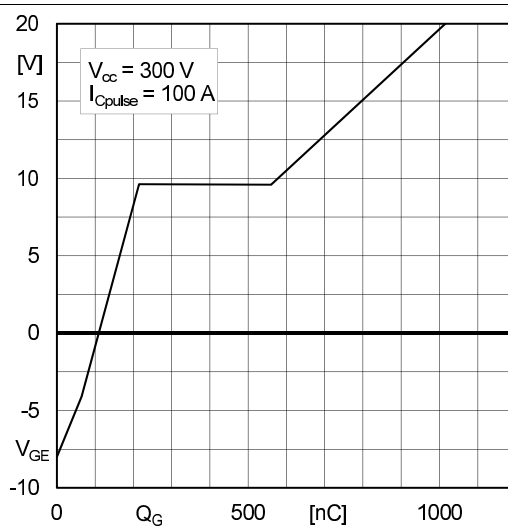


Fig. 6: Typ. IGBT1 gate charge characteristic

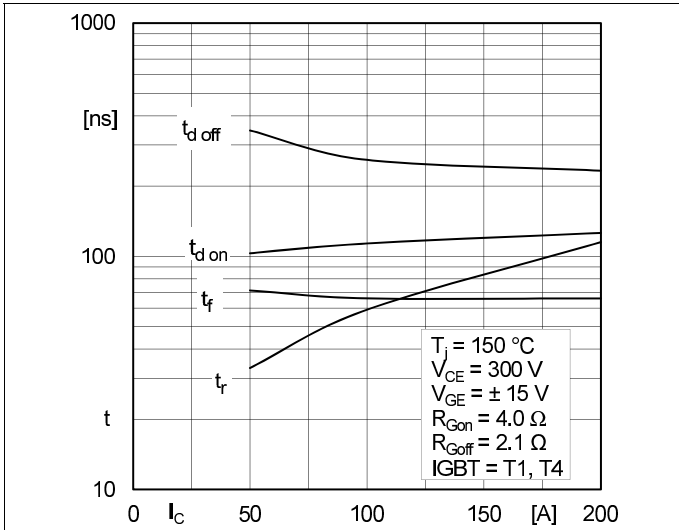


Fig. 7: Typ. IGBT1 switching times vs.  $I_c$

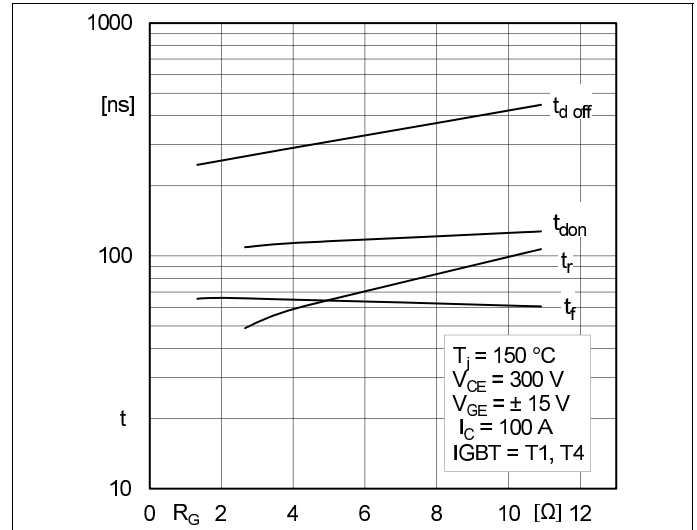


Fig. 8: Typ. IGBT1 switching times vs. gate resistor  $R_G$

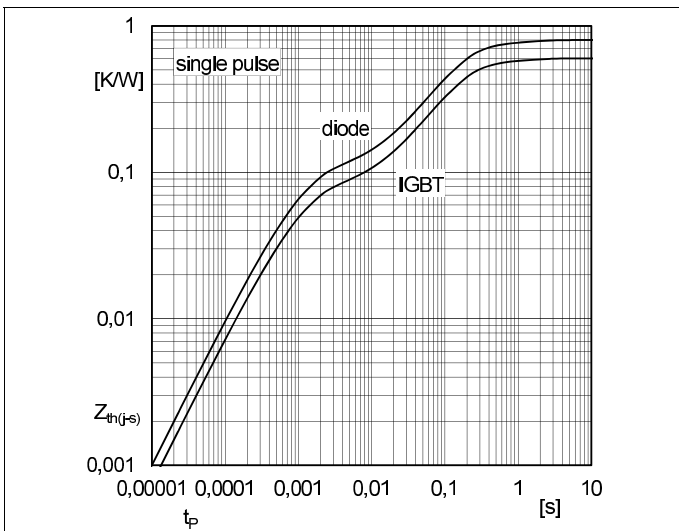


Fig. 9: Typ. transient thermal impedance of IGBT1 & Diode5

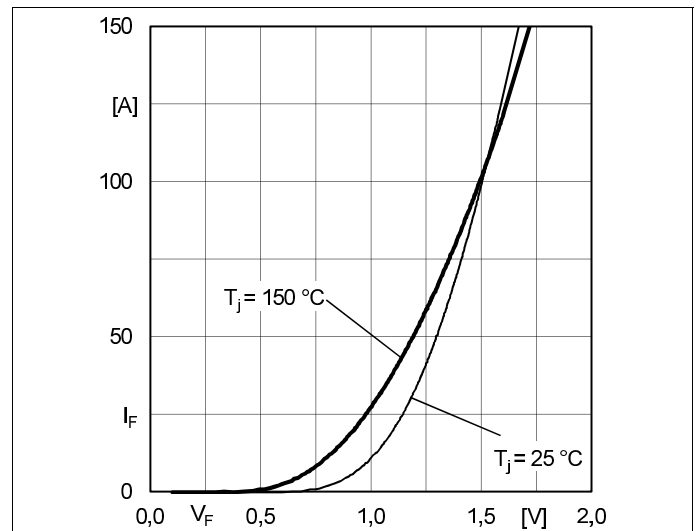


Fig. 10: Typ. Diode5 forward characteristic, incl.  $R_{CC+EE'}$

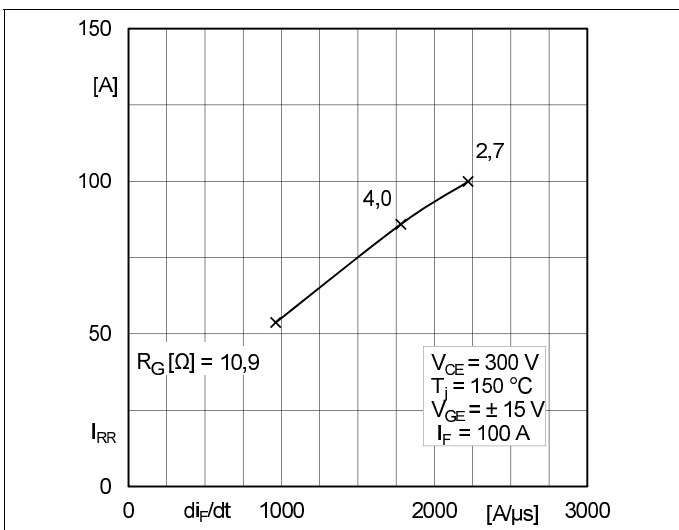


Fig. 11: Typ. Diode5 peak reverse recovery current

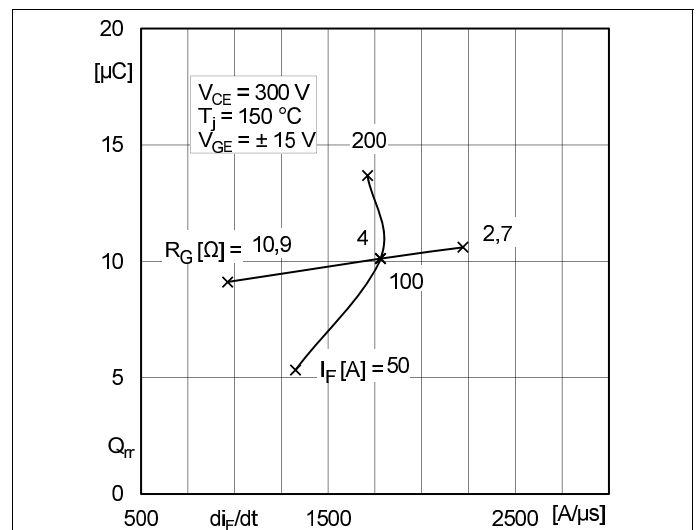
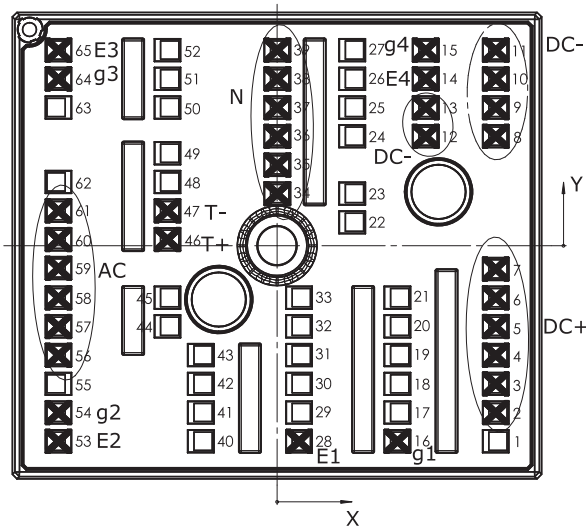


Fig. 12: Typ. Diode5 recovery charge

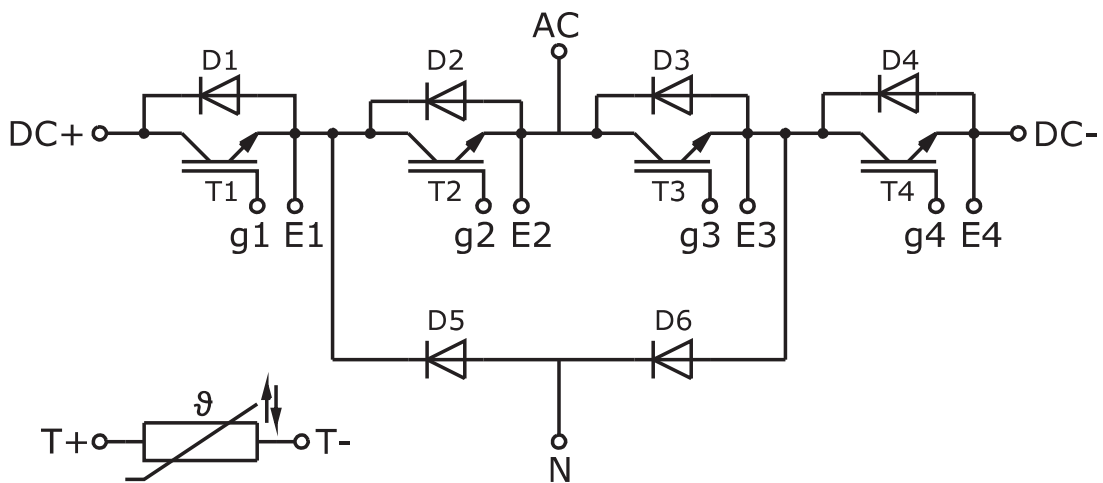
# SKiP 27MLI07E3V1

Pin out											
Pin	X	Y	Function	Pin	X	Y	Function	Pin	X	Y	Function
1	24,38	-21,80		23	8,38	5,80		45	-12,23	-5,80	
2	24,38	-18,60	DC+	24	8,38	12,20		46	-12,23	0,70	T+
3	24,38	-15,40	DC+	25	8,38	15,40		47	-12,23	3,90	T-
4	24,38	-12,20	DC+	26	8,38	18,60		48	-12,23	7,10	
5	24,38	-9,00	DC+	27	8,38	21,80		49	-12,23	10,30	
6	24,38	-5,80	DC+	28	2,46	-21,80	E1	50	-12,23	15,40	
7	24,38	-2,60	DC+	29	2,46	-18,60		51	-12,23	18,60	
8	24,38	12,20	DC-	30	2,46	-15,40		52	-12,23	21,80	
9	24,38	15,40	DC-	31	2,46	-12,20		53	-24,38	-21,80	E2
10	24,38	18,60	DC-	32	2,46	-9,00		54	-24,38	-18,60	g2
11	24,38	21,80	DC-	33	2,46	-5,80		55	-24,38	-15,40	
12	16,58	12,20	DC-	34	0,03	5,80	N	56	-24,38	-12,20	AC
13	16,58	15,40	DC-	35	0,03	9,00	N	57	-24,38	-9,00	AC
14	16,58	18,60	E4	36	0,03	12,20	N	58	-24,38	-5,80	AC
15	16,58	21,80	g4	37	0,03	15,40	N	59	-24,38	-2,50	AC
16	13,42	-21,80	G1	38	0,03	18,60	N	60	-24,38	0,70	AC
17	13,42	-18,60		39	0,03	21,80	N	61	-24,38	3,90	AC
18	13,42	-15,40		40	-8,51	-21,80		62	-24,38	7,10	
19	13,42	-12,20		41	-8,51	-18,60		63	-24,38	15,40	
20	13,42	-9,00		42	-8,51	-15,40		64	-24,38	18,60	g3
21	13,42	-5,80		43	-8,51	-12,20		65	-24,38	21,80	E3
22	8,38	2,60		44	-12,23	-9,00					

all values in mm



Pinout and Dimensions



Pinout

This is an electrostatic discharge sensitive device (ESDS) due to international standard IEC 61340.

## **\*IMPORTANT INFORMATION AND WARNINGS**

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